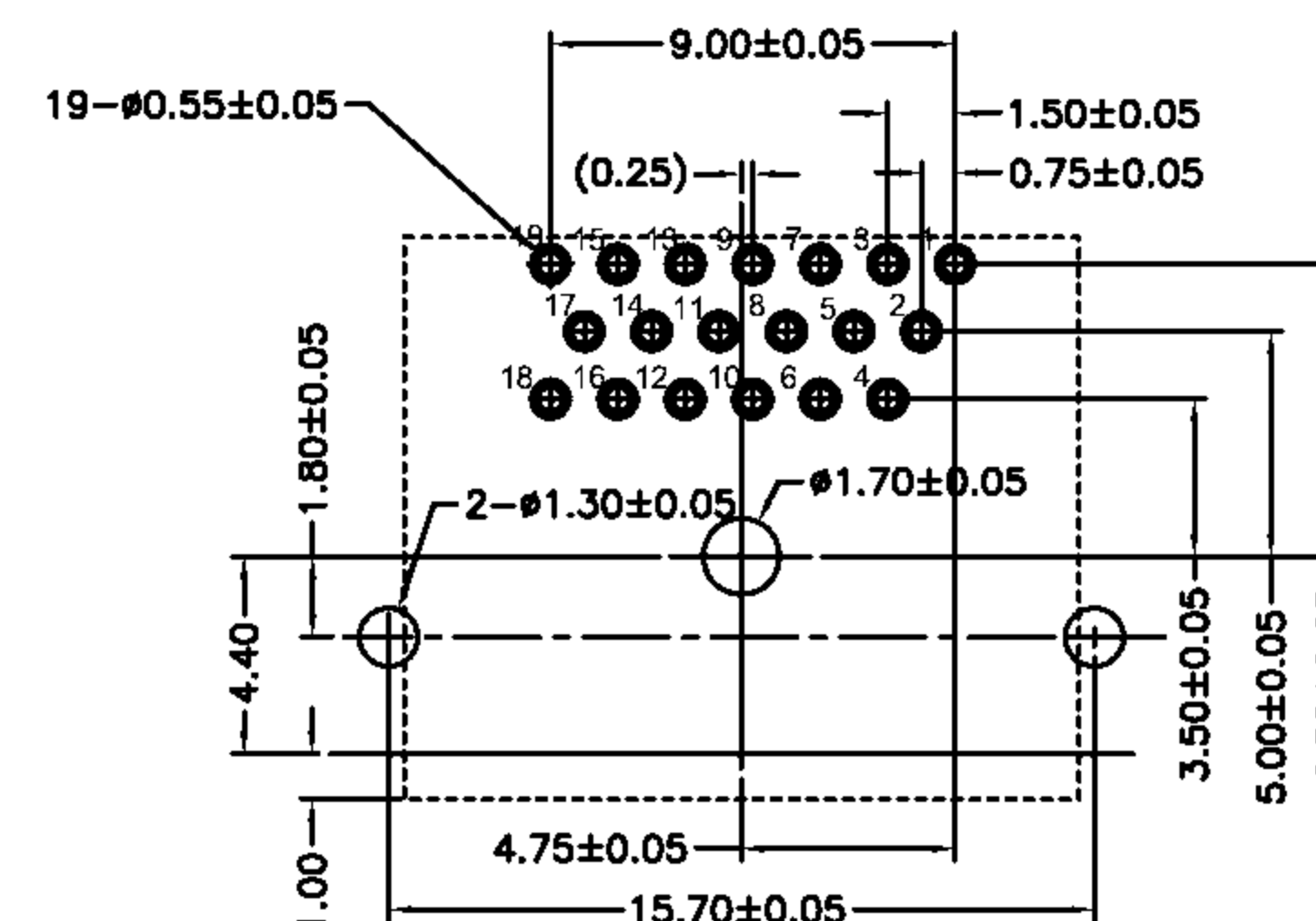
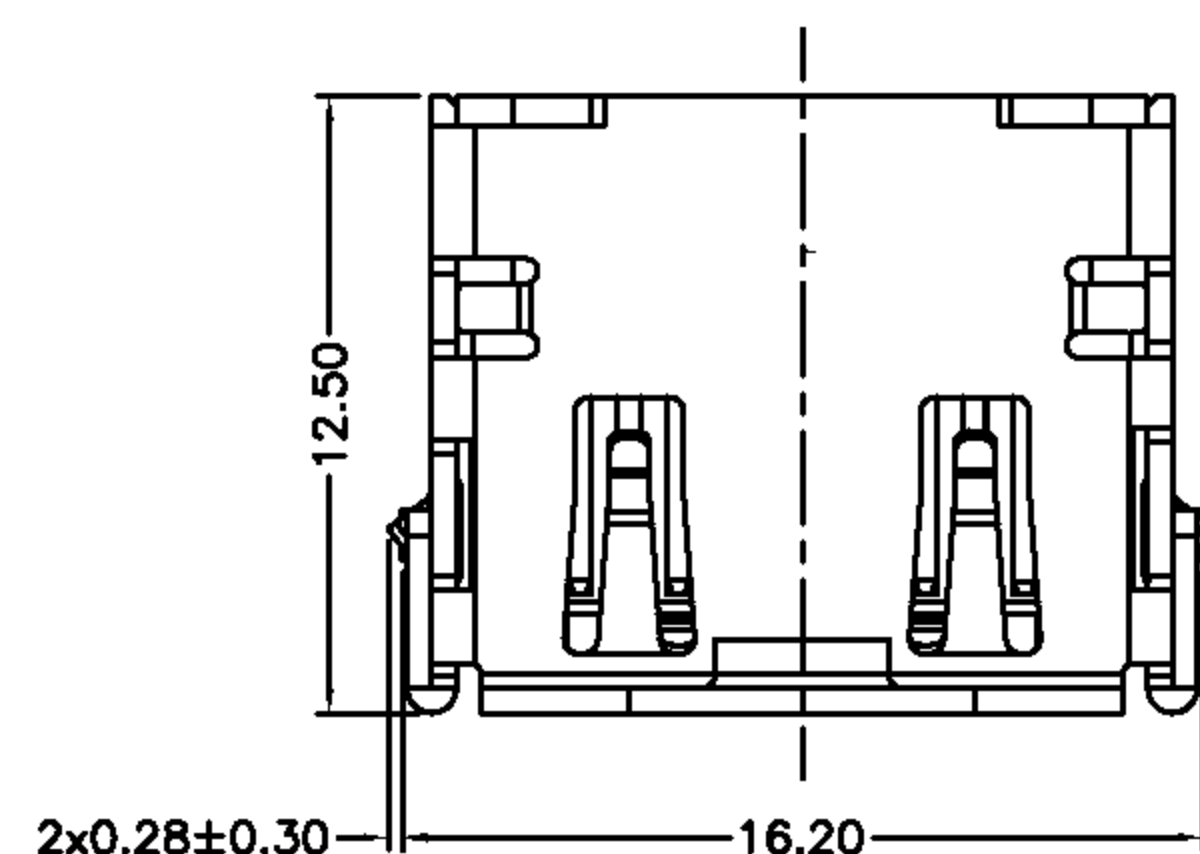


Micro-Ray



RECOMMENDED PCB LAYOUT(t=1.60±0.15)
COMPONENT SIDE

NOTE:

1.MECHANICAL CHARACTERISTICS

INSERTION FORCE: 44.1N MAX

WITHDRAWAL FORCE: 9.8N MIN, 39.2N MAX

MATING CYCLE:10000 CYCLES

CONTACT PULL OUT FORCE: 1.96N/PIN MIN

2.ELECTRICAL CHARACTERISTICS

RATING CURRENT: 0.5A

RATING VOLTAGE: 40V

CONTACT RESISTANCE: 10 MILLOHMS OHMS MAX

(EXCLUDING CONDUCTOR RESISTANCE)

INSULATION RESISTANCE:

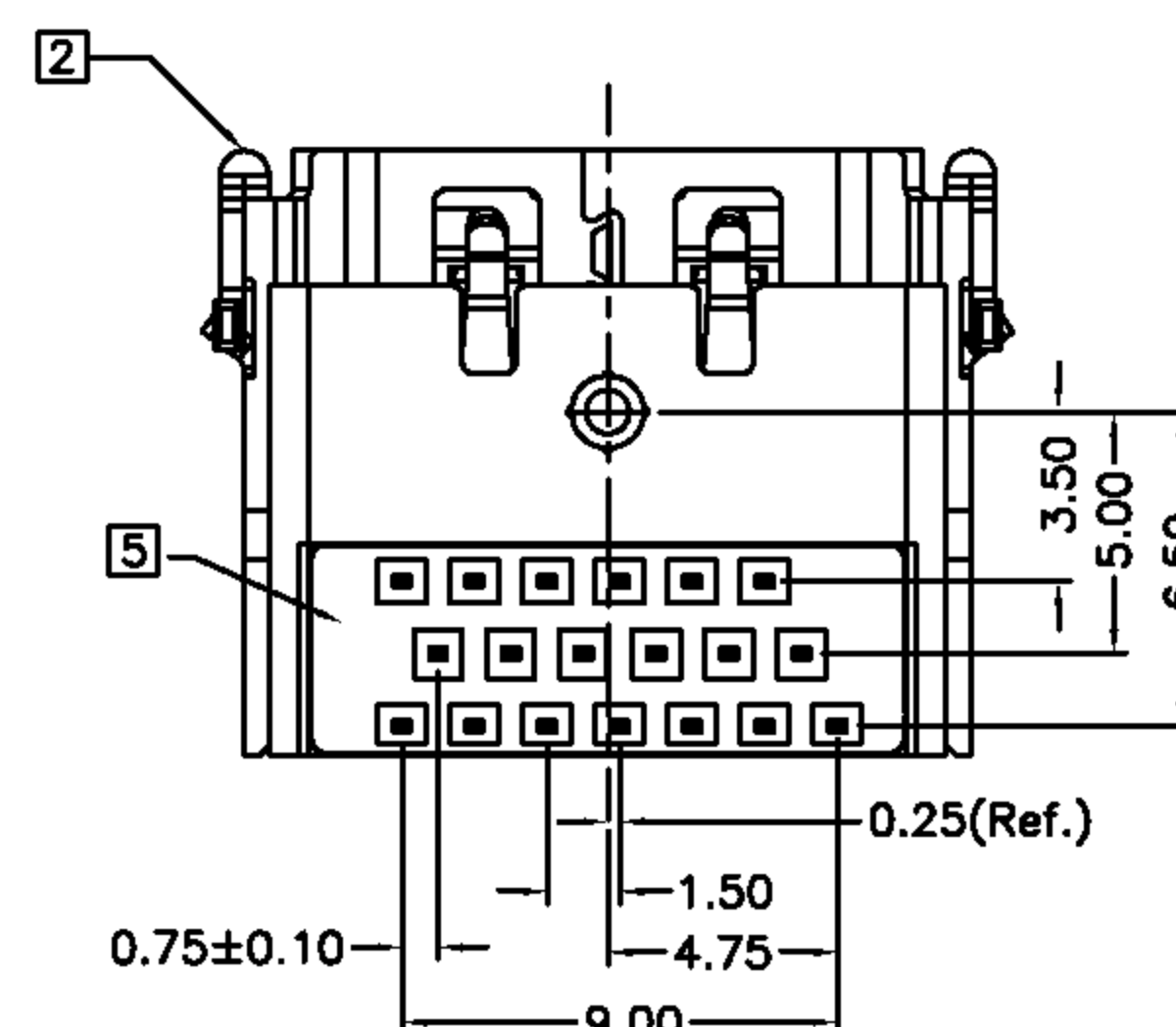
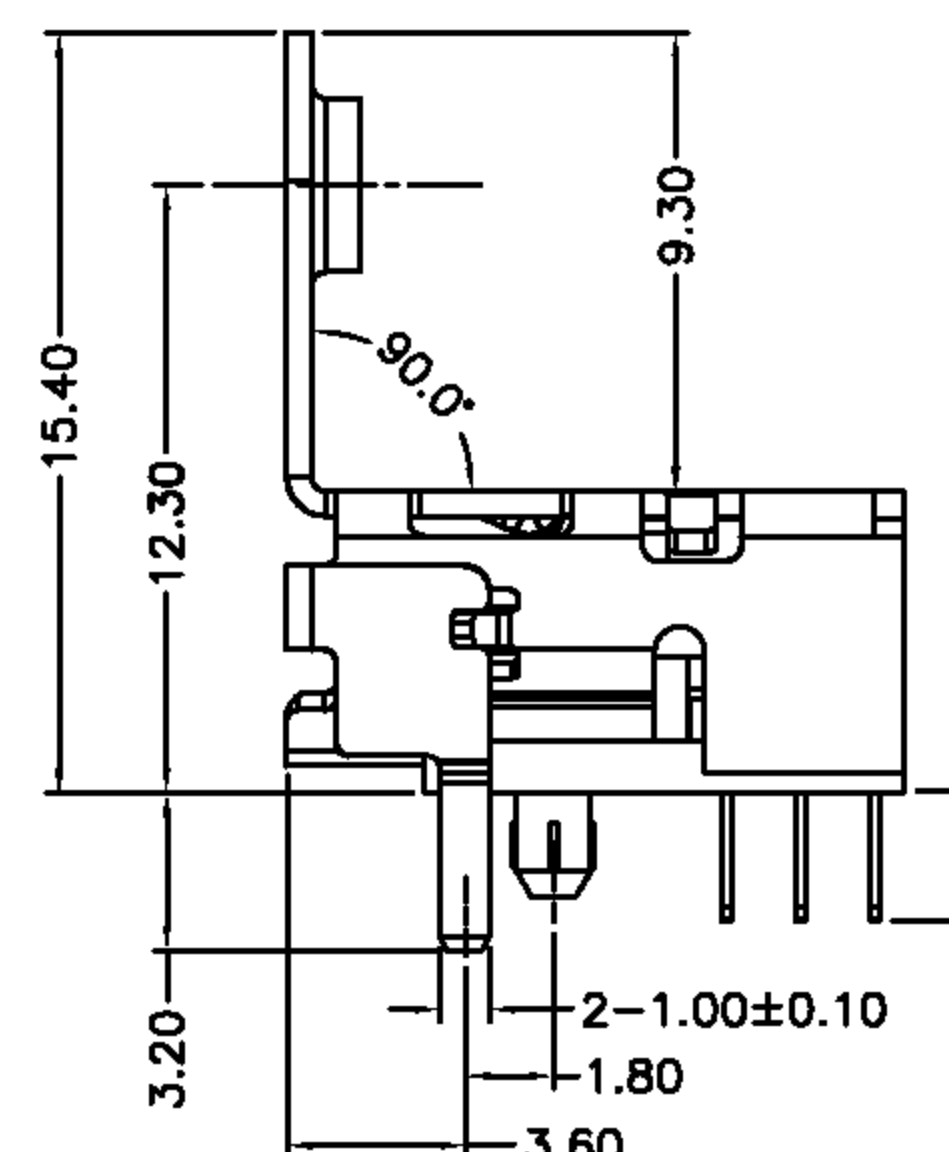
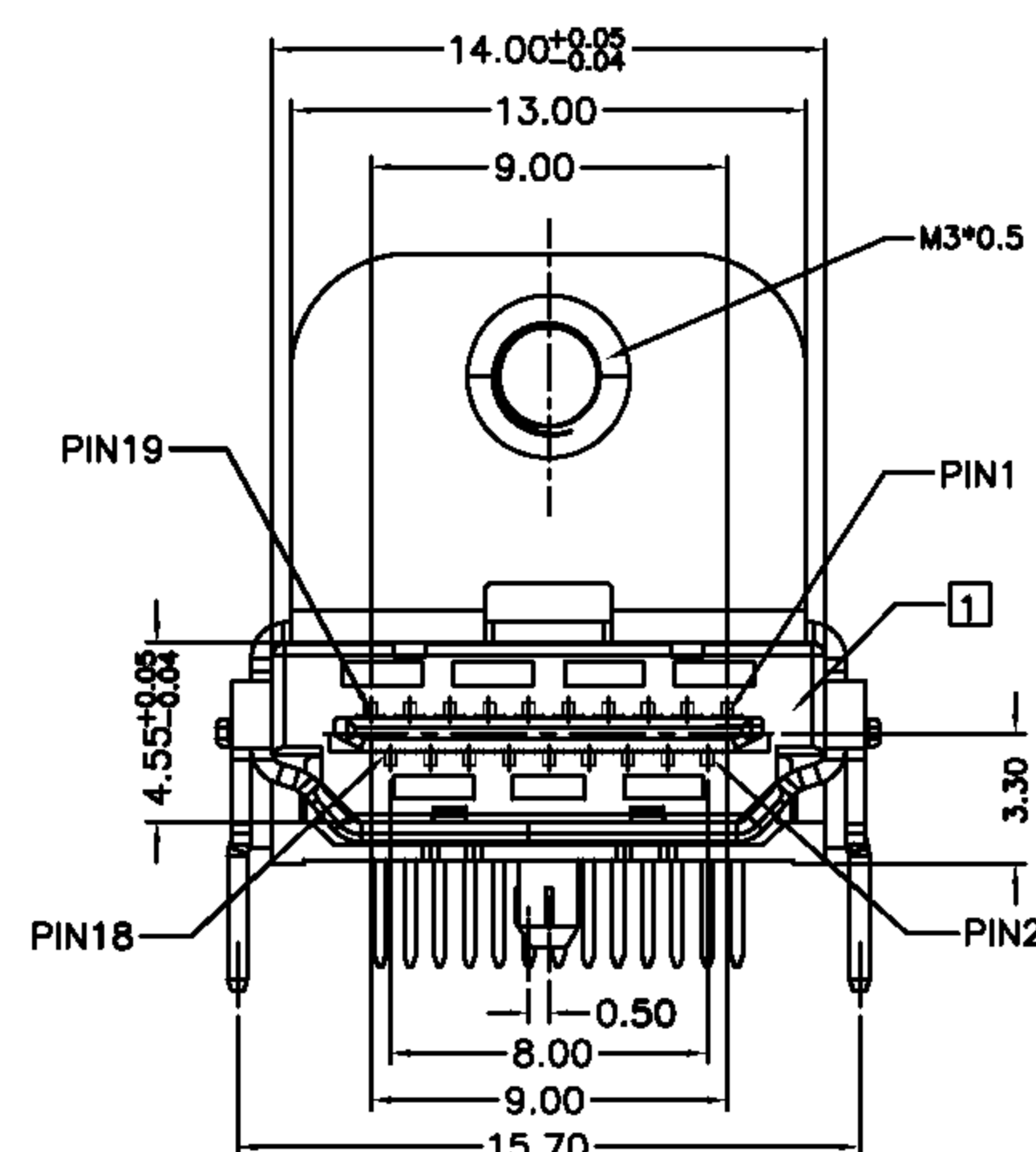
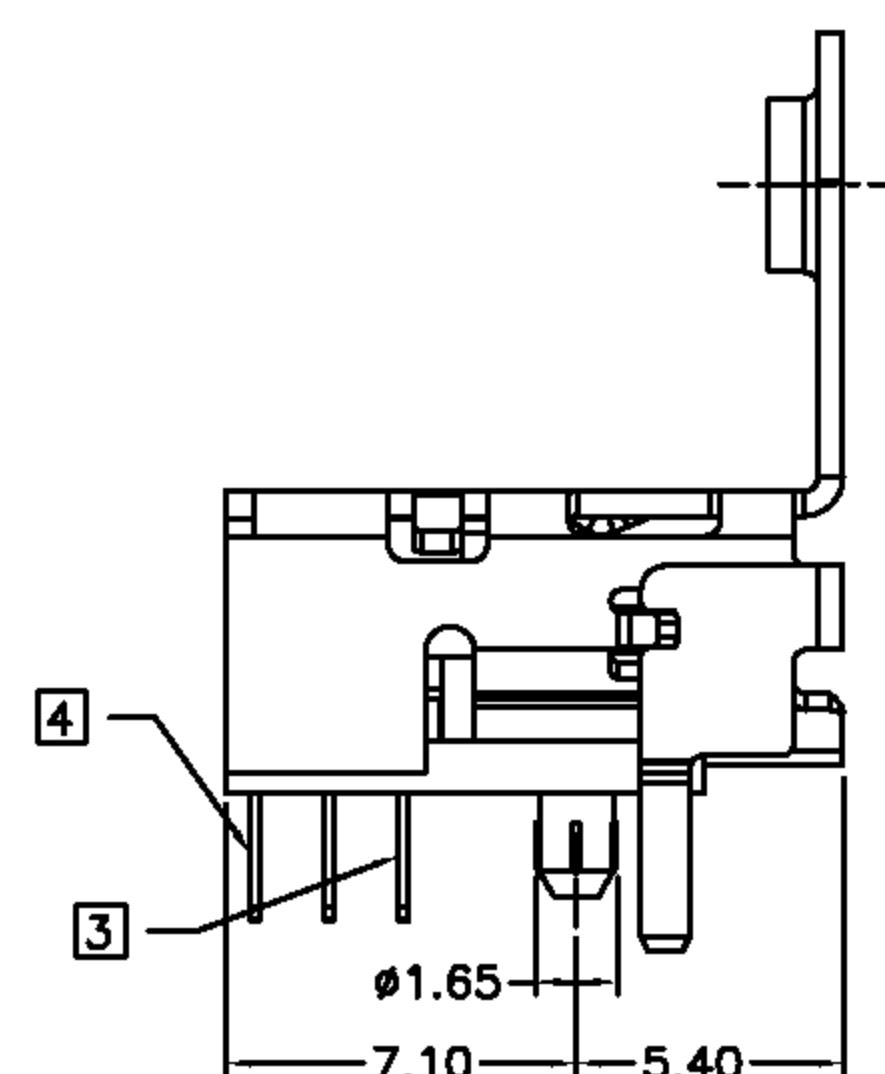
a, UNMATED: 100M OHMS MIN AT 500 VDC

b, MATED: 10M OHMS MIN AT 150 VDC

DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/1MINUTE

OPERATING TEMPERATURE: -20°C--+85°C

STORAGE TEMPERATURE: -20°C--+65°C



PART NO. INFORMATION

MR-A1119E1-X-XX-T

FORM A:ASS'y

SERIES 11:HDMI-A/F

NUMBER OF POS. 19

FOLLOW NO. E1

D: SOLDER TAIL AU PLATED

F: SOLDER TAIL MATTE TIN PLATED

PACKING TYPE T: TRAY

CONTACT AREA PLATING

01:Au 1u"

03:Au 3u"

05:Au 5u"

10:Au 10u"

15:Au 15u"

30:Au 30u"

E	TE2017-XXXX	更新产品视图错误	2017.08.31
D	TE2014-0100	变更铁壳结构	2013.12.10
C	TE2009-727	增加锡脚电镀雾锡选项	2009.12.18
B	TE2009-605	更换图框, 导入新料号, 增加无LOGO选项	2009.11.03
A	TE2008-119	DRAWING RELEASE	2008.10.14
REV	ECN NO	DESCRIPTION	DATE

04	COVER	LCP, (BLACK) UL94V-0	Black	1
03	Contact	C5210R-H	Gold plating on contact area see part no.80u"min Sn plated on solder tails.50u" min nickel under plated over all	19
02	Shell	C2680	Solderable Ni 50u"Min.	1
01	Housing	LCP	Black	1
NO.	Name	Material	Plated/Color	Note
X. ±	HDMI-A/F/19PIN/With Flange /Dip 90° /3 ROWS CONNECTOR			
.X ± 0.25				
.XX ± 0.20				
.XXX±				
X' ± 2.5°	DR: Cola Lee		PART NO: MR-A1119E1-X-XX-T	
.X' ± 2°				
	UNITS: mm	SCALE: NONE	DWG NO: C-A1119E1-A(D,F)-XX-X	SHEET:10F1
				REV: E